Abstract

Packaging Structure and Method of Acoustic Device

The disclosure provides a packaging structure and method of an acoustic device, relating the technical field of semiconductors, including: a substrate and a piezoelectric stack structure located on the substrate, a first organic material layer is disposed on the piezoelectric stack structure, a second organic material layer is disposed on the first organic material layer, the first organic material layer includes a first supporting part and a second supporting part, the second supporting part forms a first acoustic reflection structure, when being transmitted to the first acoustic reflection structure, acoustic waves can be reflected back to the effective area, so that the loss of the acoustic waves is reduced, and the performance of the acoustic device is improved. The first supporting part is matched with the second organic material layer to form a second acoustic reflection structure, so that when part of acoustic waves are not reflected back by the first acoustic reflection structure and are transmitted to the second acoustic reflection structure, the acoustic waves can be reflected back to the effective area, so that the loss of the acoustic waves is further reduced, and the performance of the acoustic device is improved.

Figure 1